

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	35	("20010002858" "20020019296" "20020180344" "20020180709" "4685771" "4688900" "4876441" "4948232" "5321533" "5333074" "5473450" "5530566" "5679414" "5751388" "5949508" "5978063" "5999239" "6019284" "6051639" "6128056" "6141071" "6195196" "6211994" "6284418" "6293470" "6310612" "6310671" "6311076" "6312304" "6316278" "6330208" "6335818" "6356376" "6362915").PN. OR ("6655788").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/01 14:48
L3	24	("20020190257" "5107175" "5124204" "5189405" "5686360" "5693956" "5757126" "5771562" "5811177" "5882761" "5952778" "5973258" "5990542" "6146225" "6149757" "6150187" "6198217" "6198220" "6268695" "6274887" "6320115" "6323416" "6413645" "6445005").PN. OR ("6965195").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/01 14:56
L4	1	"7015640".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/01 16:02
L6	2585	257/40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 16:18
L7	1723	257/94	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 17:12

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L8	2211	257/99	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 17:31
L9	1151	257/100	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 17:52
L10	3750	428/411.1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/01 17:52
S1	41	(semiconductor or die or chip or IC) with organic and flexible near substrate and substrate with transparent	USPAT	OR	ON	2006/07/06 20:46
S2	6	(semiconductor or die or chip or IC) near organic and flexible near substrate and substrate with transparent	USPAT	OR	ON	2006/07/06 20:51
S3	366	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent	USPAT	OR	ON	2006/07/06 20:59
S4	0	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent and substrate with wrap	USPAT	OR	ON	2006/07/06 20:59
S5	2	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent and substrate with wrap\$4	USPAT	OR	ON	2006/07/06 21:00
S6	160	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent and substrate with cover\$3	USPAT	OR	ON	2006/07/06 22:26

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S7	0	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent and "6965195".pn.	USPAT	OR	ON	2006/07/06 21:25
S8	1	"2003062527".pn. or "2002068143".pn. or "6080031".pn. or "2003104753".pn.	US-PGPUB; USPAT	OR	ON	2006/07/06 21:30
S9	1	"2003062527".pn. or "2002068143".pn. or "6080031".pn. or "2003104753".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/06 21:27
S10	1	"2003062527".pn. or "2002068143".pn. or "6080031".pn. or "2003104753".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/06 21:27
S11	0	"2003062527".pn. or "2002068143".pn. or "2003104753".pn.	US-PGPUB; USOCR	OR	ON	2006/07/06 21:27
S12	0	"2003062527".pn. or "2002068143".pn. or "2003104753".pn.	US-PGPUB	OR	ON	2006/07/06 21:28
S13	418	257/777	US-PGPUB	OR	ON	2006/07/06 21:30
S14	1	"2003/062527".pn. or "2002/068143".pn. or "6080031".pn. or "2003/104753".pn.	US-PGPUB; USPAT	OR	ON	2006/07/06 21:29
S15	1	"2003062527".pn. or "2002068143".pn. or "6080031".pn. or "2003104753".pn.	US-PGPUB; USPAT	OR	ON	2006/07/06 21:29
S16	12	"2003062527".pn. or "2002068143".pn. or "6080031".pn. or "2003104753".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 21:29
S17	4	"2003062527".pn. or "2002068143".pn. or "6080031".pn. or "20030104753".pn.	US-PGPUB; USPAT	OR	ON	2006/07/06 21:31
S18	2382	257/40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/06 22:06
S19	1630	257/94	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/06 22:20

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S20	2	"6737753".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/06 22:20
S21	6	("5920080" "6244441" "6291126" "6333537" "6522067" "6570325").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/06 22:25
S22	11	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent and warp\$4	USPAT	OR	ON	2006/07/06 23:36
S23	35	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent and bend\$3 with substrate	USPAT	OR	ON	2006/07/06 22:52
S24	10	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent and cover\$3 with (edge or perimeter) with substrate	USPAT	OR	ON	2006/07/06 22:54
S25	10	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and cover\$3 with (edge or perimeter) with substrate	USPAT	OR	ON	2006/07/06 22:57
S26	35	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and cover\$3 with (edge or perimeter)	USPAT	OR	ON	2006/07/06 23:01
S27	0	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and surround\$3 with (edge or perimeter)	USPAT	OR	ON	2006/07/06 23:01
S28	8	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and surround\$3 with (edge or perimeter)	USPAT	OR	ON	2006/07/06 23:04

EAST Search History

S29	2	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and ("U" or "C") near shaped with (edge or perimeter)	USPAT	OR	ON	2006/07/06 23:05
S30	9	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent and ("U" or "C") near shaped	USPAT	OR	ON	2006/07/06 23:10
S31	367	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED or OELD) and flexible near substrate and substrate with transparent	USPAT	OR	ON	2006/07/06 23:10
S32	41	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with transparent and fold\$3	USPAT	OR	ON	2006/07/06 23:50
S33	47	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with (translucent or glass) and fold\$3	USPAT	OR	ON	2006/07/07 00:06
S34	0	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible near substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 00:06
S35	0	((semiconductor or die or chip or IC or led or emitt\$3) same organic or OLED) and flexible near substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 01:47
S36	0	((semiconductor or die or chip or IC or led or emitt\$3) or OLED) and flexible near substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 00:06
S37	1	((semiconductor or die or chip or IC or led or emitt\$3) or OLED) and flexible with substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 00:07

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S38	1	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible with substrate and substrate with (translucent or glass) and "6965195".pn.	USPAT	OR	ON	2006/07/07 01:18
S39	23	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible with substrate and substrate with (translucent or glass) and clip	USPAT	OR	ON	2006/07/07 01:26
S40	0	((semiconductor or die or chip or IC or led or emitt\$3) with organic or OLED) and flexible with substrate and substrate with (translucent or glass) and clip with metal	USPAT	OR	ON	2006/07/07 01:26
S41	0	((led or emitt\$3) with organic or OLED) and flexible with substrate and substrate with (translucent or glass) and clip with metal	USPAT	OR	ON	2006/07/07 01:26
S42	1	((led or emitt\$3) with organic or OLED) and flexible with substrate and clip with metal	USPAT	OR	ON	2006/07/07 01:27
S43	110	((led or emitt\$3) with organic or OLED) and substrate with (clip or frame) with metal	USPAT	OR	ON	2006/07/07 01:42
S44	0	((led or emitt\$3) with organic or OLED) and substrate with (clip or frame) with copper	USPAT	OR	ON	2006/07/07 01:42
S45	302	(semiconductor or die or chip) and substrate with (clip or frame) with copper	USPAT	OR	ON	2006/07/07 01:42
S46	63	(semiconductor or die or chip) and substrate with (clip) with metal	USPAT	OR	ON	2006/07/07 01:54
S47	6	(organic near optoelectronic same (organic near photovoltaic with OLED))	USPAT	OR	ON	2006/07/07 01:48
S48	0	(semiconductor or die or chip) and substrate with (clip) with metal with polyimide	USPAT	OR	ON	2006/07/07 01:55
S49	1	(semiconductor or die or chip) and substrate same clip with metal with polyimide	USPAT	OR	ON	2006/07/07 01:56
S50	4	(semiconductor or die or chip) and substrate same clip with metal with rubber	USPAT	OR	ON	2006/07/07 01:56

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S51	4	(semiconductor or die or chip) and substrate same clip with metal with polymer	USPAT	OR	ON	2006/07/07 01:58
S52	0	(semiconductor or die or chip) and substrate same flexible near frame with metal with polymer	USPAT	OR	ON	2006/07/07 01:58
S53	0	(semiconductor or die or chip) and substrate and flexible near frame with metal with polymer	USPAT	OR	ON	2006/07/07 02:01
S54	5	(semiconductor or die or chip) and substrate and clip with metal with polymer	USPAT	OR	ON	2006/07/07 01:58
S55	2	(semiconductor or die or chip) and substrate and flexible near frame with metal with (polymer or rubber or polyimide)	USPAT	OR	ON	2006/07/07 02:02
S56	0	(semiconductor or die or chip) and substrate and flexible near frame with foil with (polymer or rubber or polyimide)	USPAT	OR	ON	2006/07/07 02:02
S57	2	(semiconductor or die or chip) and substrate and clip with foil with (polymer or rubber or polyimide)	USPAT	OR	ON	2006/07/07 02:05
S58	2	(semiconductor or die or chip) and substrate and clip with foil with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:12
S59	3	(semiconductor or die or chip) and substrate and clamp with foil with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:05
S60	29	(semiconductor or die or chip) and substrate and clip with metal with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:12
S61	4	(semiconductor or die or chip) and substrate and clip with made with metal with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:13
S62	9	(semiconductor or die or chip) and substrate and clip with formed with metal with (polymer or rubber or polyimide or resin)	USPAT	OR	ON	2006/07/07 02:17
S63	13	(semiconductor or die or chip) and substrate and clip with formed with metal with (plastic)	USPAT	OR	ON	2006/07/07 02:17